

Abstract

**Method for Cooling a Workpiece made of Semiconductor
Material during Wire Sawing**

The present invention relates to a method for cooling a cylindrical workpiece made of semiconductor material, for example silicon, germanium or gallium arsenide, during wire sawing, a liquid coolant being applied onto the semiconductor material workpiece by means of nozzles during the cutting. Wipers bearing on the workpiece prevent the liquid coolant from being mixed with the cutting suspension.

Fig. 2